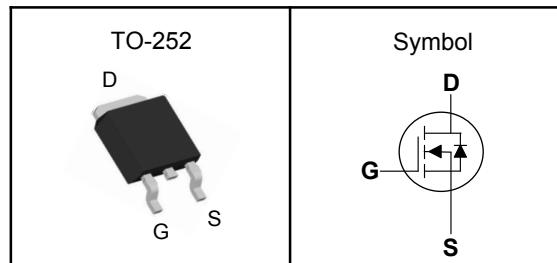


## N-Channel Enhancement Mode MOSFET

### Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant
- 100% UIS and Rg Tested

### Pin Description



### Applications

- Power Management in Desktop Computer
- DC/DC Converters

$V_{DSS}$	60	V
$R_{DS(ON)-Typ}$	14	$\text{m}\Omega$
$I_D$	42	A

### Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
$V_{DSS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$E_{AS}$	Single Pulse Avalanche Energy <sup>③</sup>	26	mJ
$I_{DM}^{①}$	Pulse Drain Current Tested	104	A
$I_D$	Continuous Drain Current	$T_c=25^\circ\text{C}$	A
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	W

### Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sub>1</sub> (Max)	55	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sub>1</sub>	2.3	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ\text{C}$ .

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

## N-Channel Enhancement Mode MOSFET

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\text{mA}$	60	---	---	V
$\text{I}_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$	---	---	1	$\mu\text{A}$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	1.0	---	2.5	V
$\text{I}_{\text{GSS}}$	Gate Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
$R_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	14	17	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=5\text{A}$	---	15	19.5	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>⑤</sup></b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=30\text{V}$ , Freq.=1MHz	---	2170	---	pF
$C_{\text{oss}}$	Output Capacitance		---	112	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	87	---	
$T_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ , $I_D=1\text{A}$	---	9	---	nS
$T_r$	Turn-on Rise Time		---	18	---	
$T_{\text{d(off)}}$	Turn-off Delay Time		---	40	---	
$T_f$	Turn-off Fall Time		---	30	---	
$Q_g$	Total Gate Charge	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	---	52	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	10	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	8	---	
<b>Source-Drain Characteristics</b> ( $T_J=25^\circ\text{C}$ )						
$V_{\text{SD}}$	Diode Forward Voltage <sub>2</sub>	$V_{\text{GS}}=0\text{V}$ , $I_S=1\text{A}$ , $T_J=25^\circ\text{C}$	---	0.7	1.1	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	18	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	11.5	---	nC

Note ④ : Pulse test (pulse width $\leq 300\text{us}$ , duty cycle $\leq 2\%$ ).

Note ⑤ : Guaranteed by design, not subject to production testing.

## N-Channel Enhancement Mode MOSFET

### Typical Characteristics

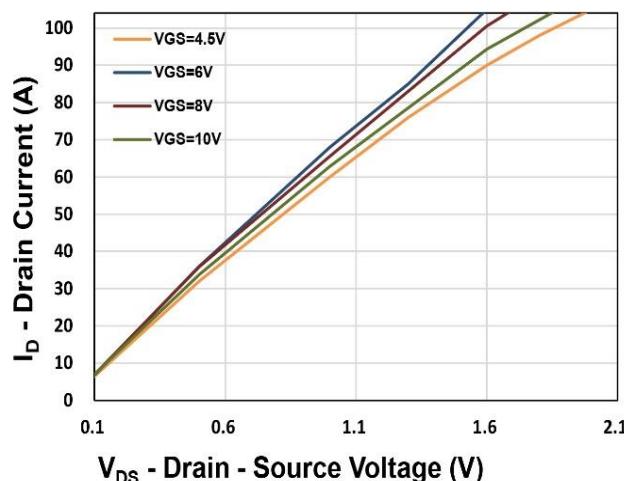


Figure 1. Output Characteristics

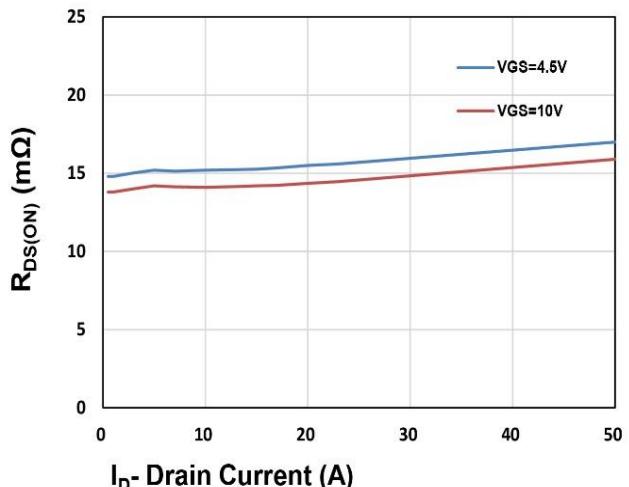


Figure 2. On-Resistance vs. ID

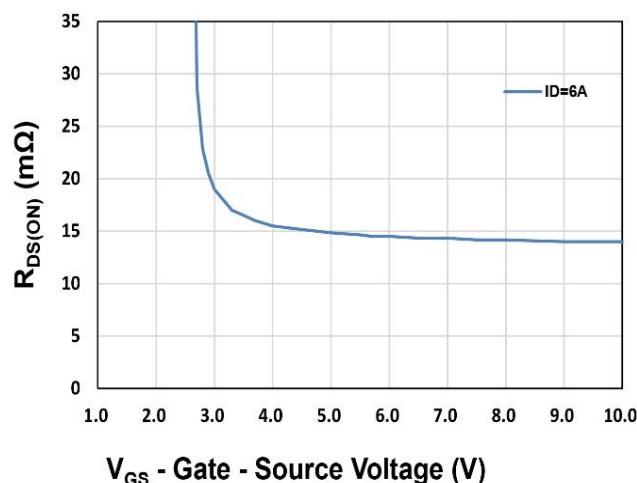


Figure 3. On-Resistance vs. VGS

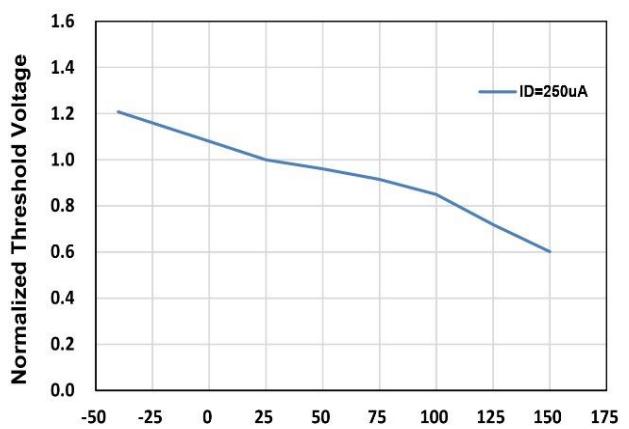


Figure 4. Gate Threshold Voltage

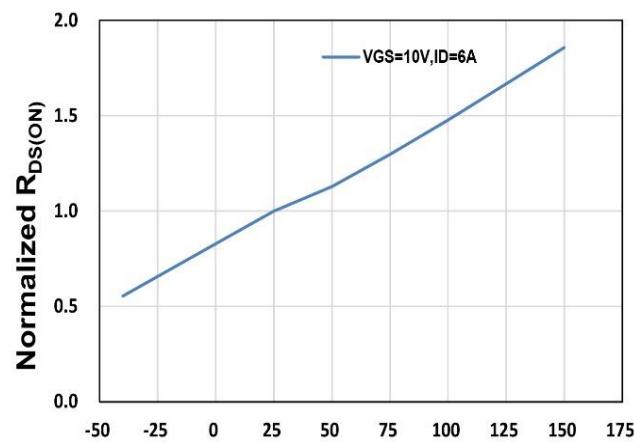


Figure 5. Drain-Source On Resistance

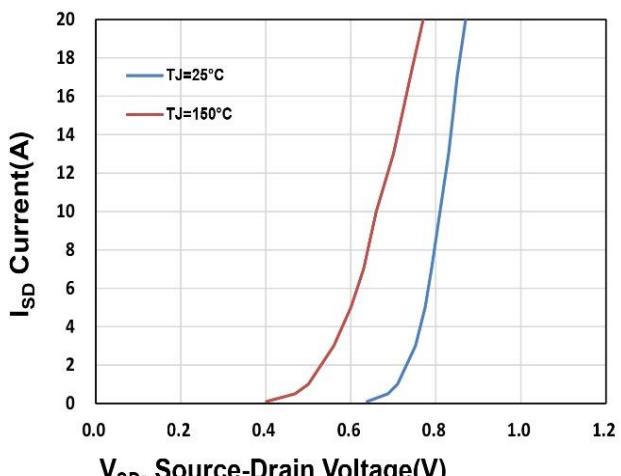
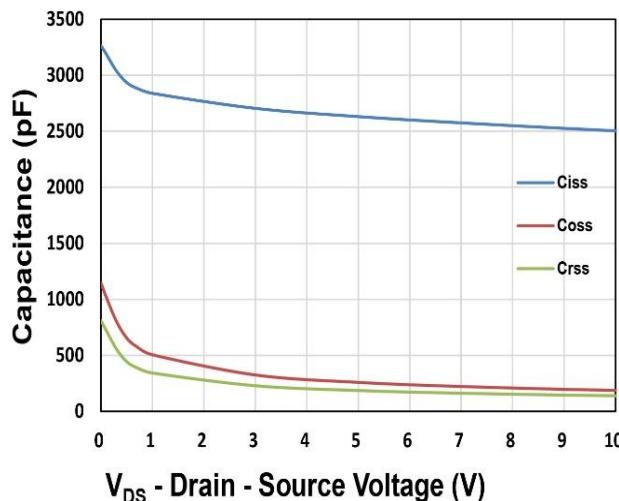


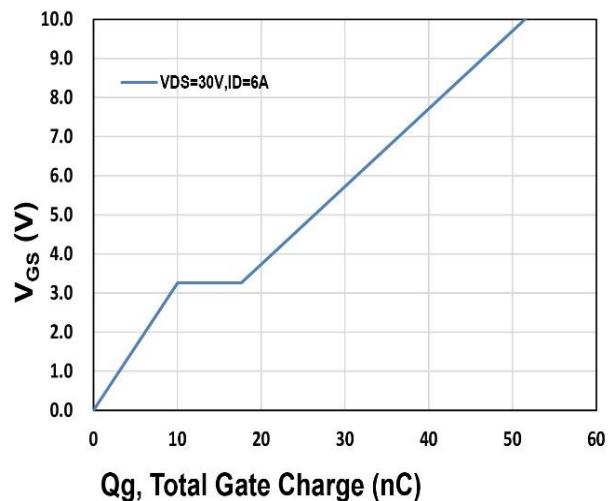
Figure 6. Source-Drain Diode Forward

## N-Channel Enhancement Mode MOSFET



V<sub>DS</sub> - Drain - Source Voltage (V)

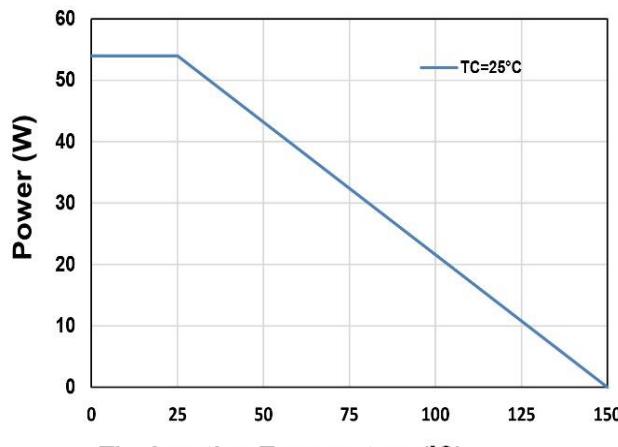
Figure 7. Capacitance



V<sub>GS</sub> (V)

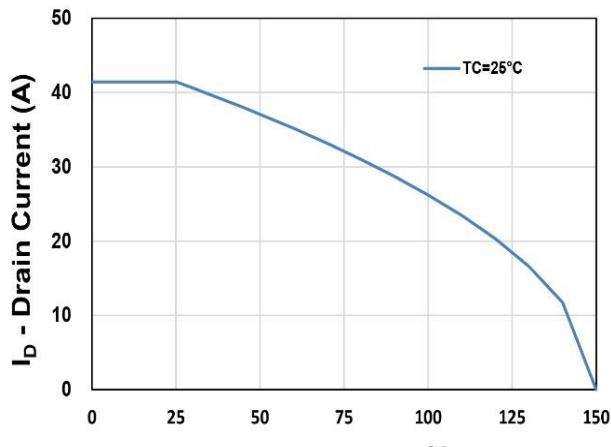
Q<sub>g</sub>, Total Gate Charge (nC)

Figure 8. Gate Charge Characteristics



T<sub>j</sub> - Junction Temperature (°C)

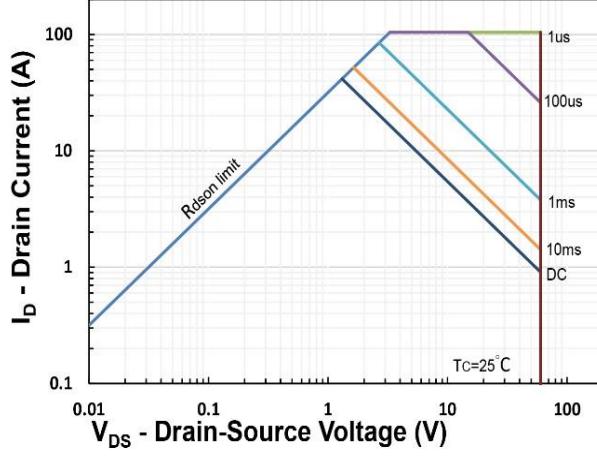
Figure 9. Power Dissipation



I<sub>D</sub> - Drain Current (A)

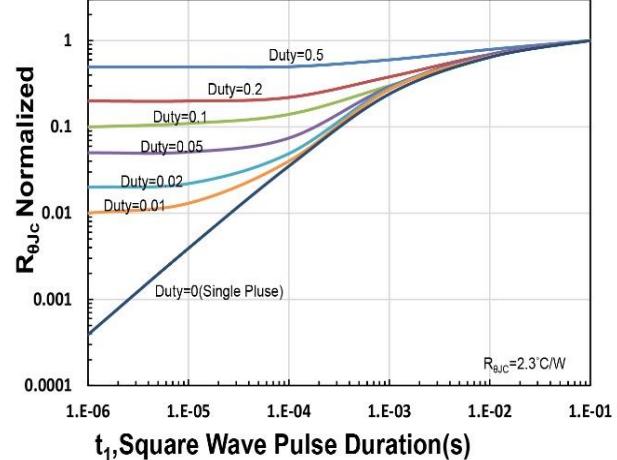
T<sub>j</sub> - Junction Temperature (°C)

Figure 10. Drain Current



V<sub>DS</sub> - Drain-Source Voltage (V)

Figure 11. Safe Operating Area



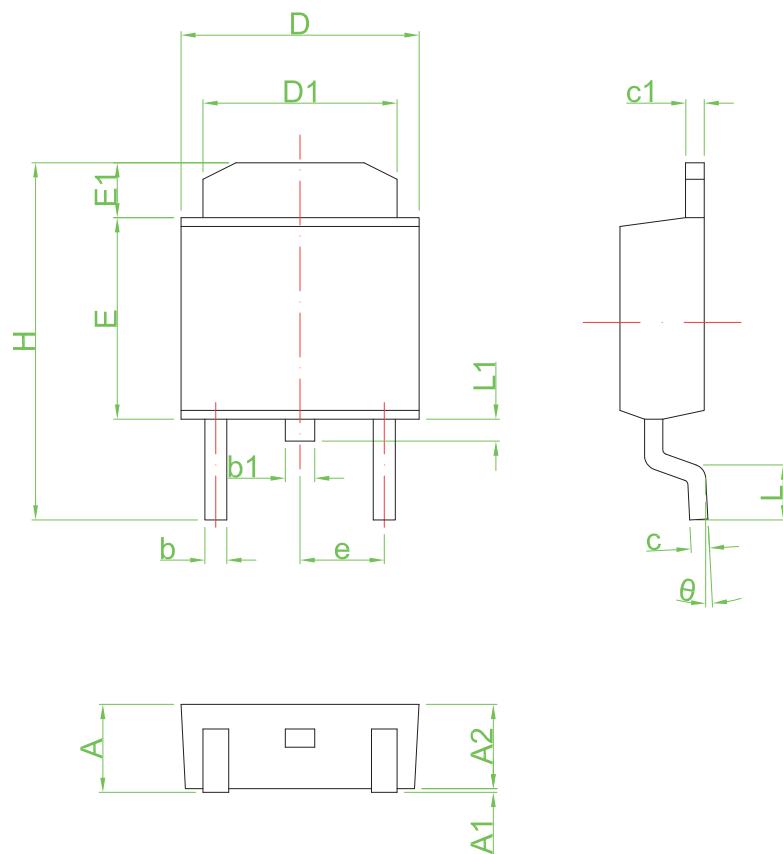
R<sub>ejc</sub> Normalized

t<sub>1</sub>, Square Wave Pulse Duration(s)

Figure 12. R<sub>ejc</sub> Transient Thermal Impedance

## N-Channel Enhancement Mode MOSFET

### TO-252 Package Outline Dimensions



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	2.25	2.65	0.089	0.104
A1	0.00	0.15	0.000	0.006
A2	2.20	2.40	0.087	0.094
b	0.50	0.70	0.020	0.028
b1	0.70	0.90	0.028	0.035
c	0.46	0.66	0.018	0.026
c1	0.46	0.66	0.018	0.026
D	6.30	6.70	0.248	0.264
D1	5.20	5.40	0.205	0.213
E	5.30	5.70	0.209	0.224
E1	1.40	1.60	0.055	0.063
H	9.40	9.90	0.370	0.390
e	2.30 TYP		0.09 TYP	
L	1.40	1.77	0.055	0.070
L1	0.50	0.70	0.020	0.028
θ	0°	8°	0°	8°